

SOT1306-1

Plastic very thin fine-pitch ball grid array package; 64 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA64
Package type industry code	VFBGA64
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	10-6-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.1	-	5.2	5.3	mm
E	package width	5.1	-	5.2	5.3	mm
A	seated height	0.8	-	0.9	1	mm
A ₂	package height	0.65	-	0.7	0.75	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	64	-	



2. Package outline

VFBGA64: plastic very thin fine-pitch ball grid array package; 64 balls;

SOT1306-1

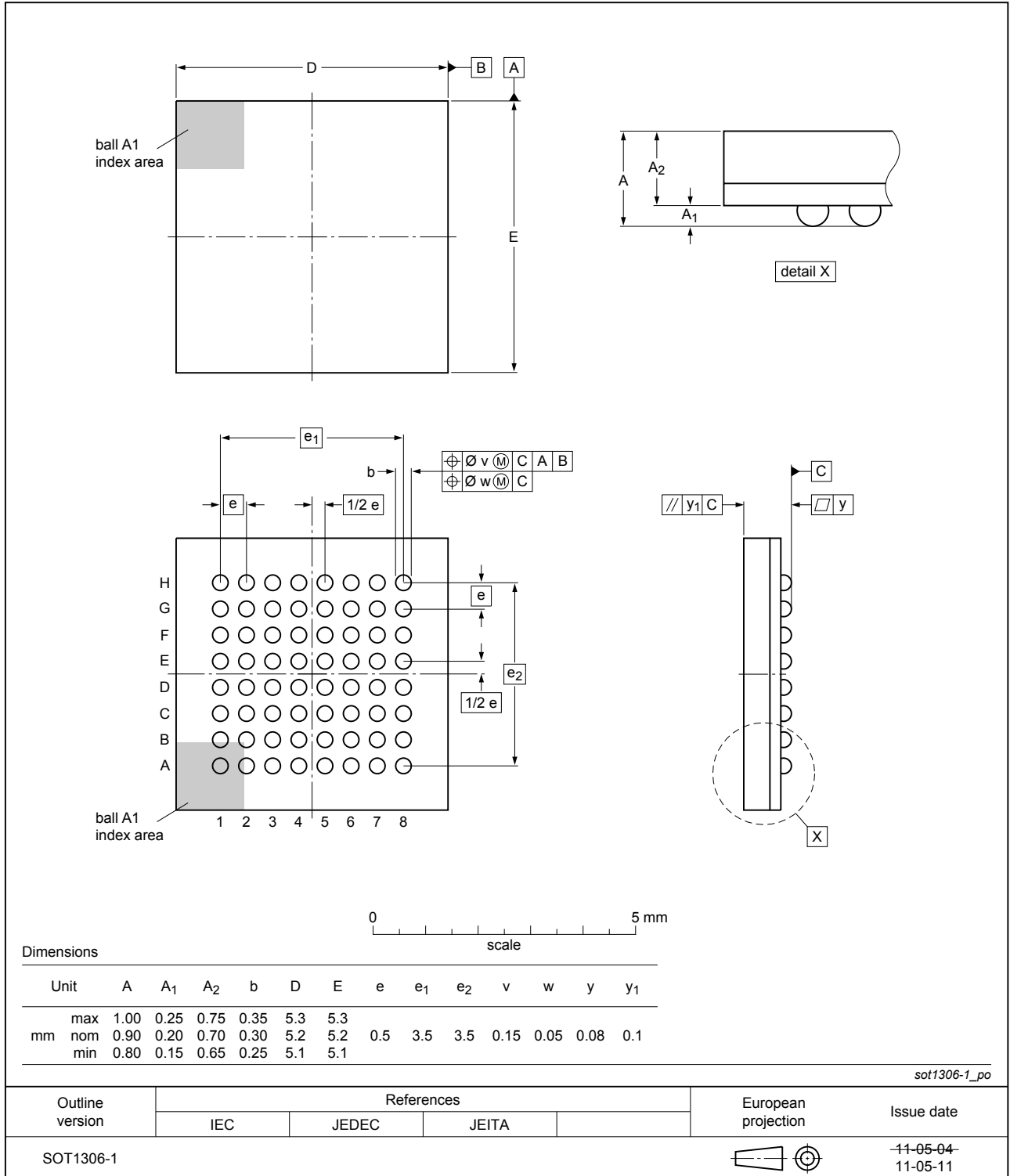


Fig. 1. Package outline VFBGA64 (SOT1306-1)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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